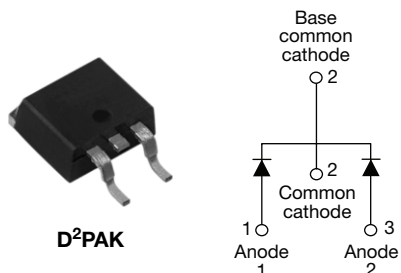


Schottky Rectifier, 2 x 15 A



FEATURES

- 150 °C T_J operation
- Center tap configuration
- Very low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Halogen-free according to IEC 61249-2-21 definition
- Compliant to RoHS directive 2002/95/EC
- AEC-Q101 qualified



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY

$I_{F(AV)}$	2 x 15 A
V_R	30 V

DESCRIPTION

This center tap Schottky rectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	30	A
V_{RRM}		30	V
I_{FSM}	$t_p = 5 \mu s$ sine	1100	A
V_F	15 Apk, $T_J = 125^\circ C$ (per leg)	0.34	V
T_J	Range	- 55 to 150	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-MBRB3030CTLPbF	UNITS
Maximum DC reverse voltage	V_R	30	V
Maximum working peak reverse voltage	V_{RWM}		

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current per leg See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 121^\circ C$ rectangular waveform	15	A
			30	
Maximum peak one cycle non-repetitive surge current per leg See fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	1100	
		10 ms sine or 6 ms rect. pulse	360	
Non-repetitive avalanche energy per leg	E_{AS}	$T_J = 25^\circ C$, $I_{AS} = 3 A$, $L = 2.9 mH$	13	mJ
Repetitive avalanche current per leg	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical	3	A

ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS	
Maximum forward voltage drop per leg See fig. 1	$V_{FM}^{(1)}$	15 A	$T_J = 25\text{ }^{\circ}\text{C}$	0.47	V	
		30 A		0.55		
		15 A	$T_J = 125\text{ }^{\circ}\text{C}$	0.34		0.45
		30 A				
Maximum reverse leakage current per leg See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{Rated } V_R$	2	mA	
		$T_J = 125\text{ }^{\circ}\text{C}$		183		
Threshold voltage	$V_{F(TO)}$	$T_J = T_J \text{ maximum}$		0.22	V	
Forward slope resistance	r_t			6.76	mΩ	
Maximum junction capacitance per leg	C_T	$V_R = 5\text{ }V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		2840	pF	
Typical series inductance per leg	L_S	Measured lead to lead 5 mm from package body		8.0	nH	
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/μs	

Note(1) Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		- 55 to 150	°C
Maximum thermal resistance, per leg junction to case per package	R _{thJC}	DC operation	2.0	°C/W
			1.0	
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased	0.50	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum		6 (5)	kgf · cm (lbf · in)
	maximum		12 (10)	
Marking device		Case style D ² PAK	MBRB3030CTL	

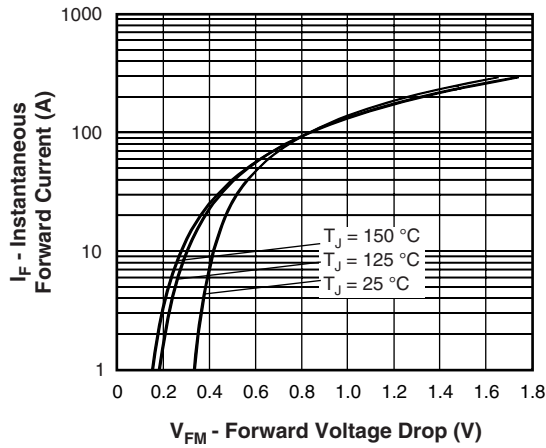


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

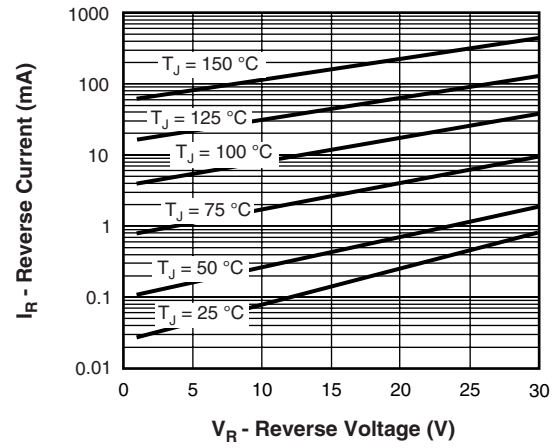


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

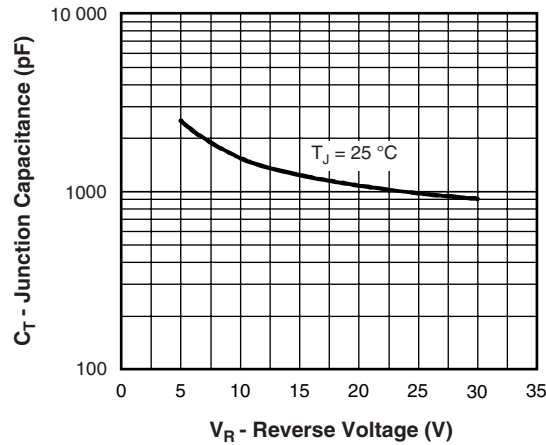


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

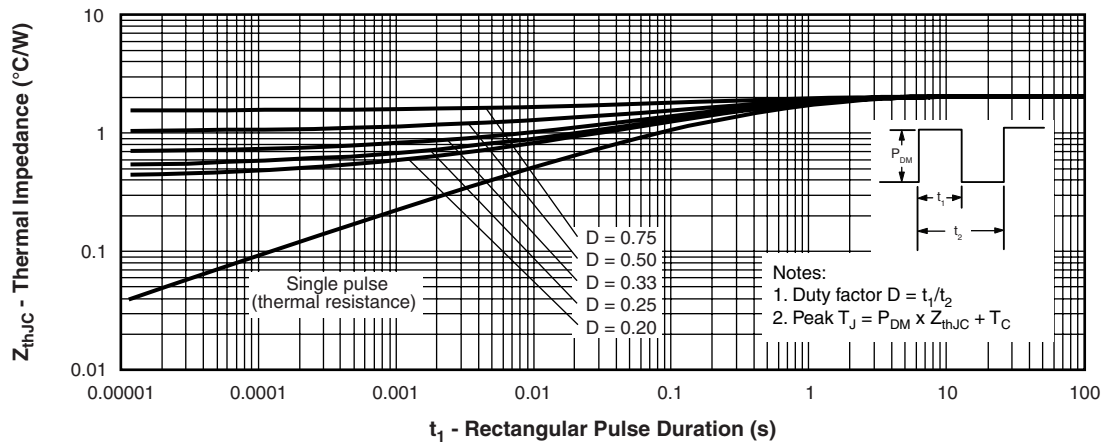


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

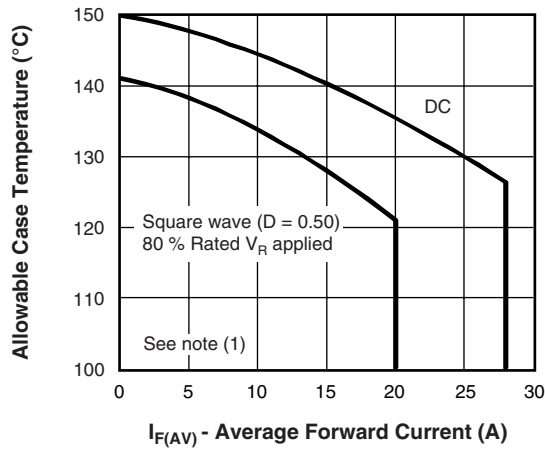


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

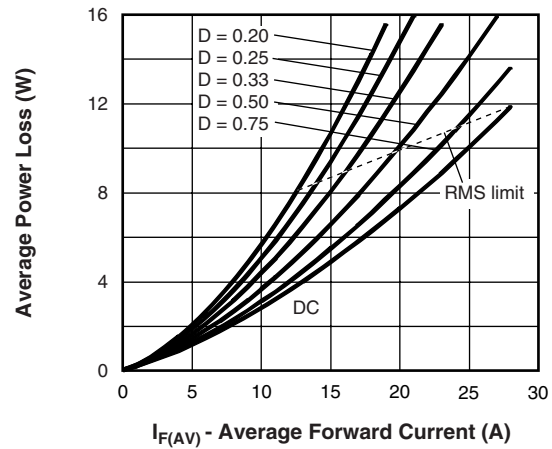


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

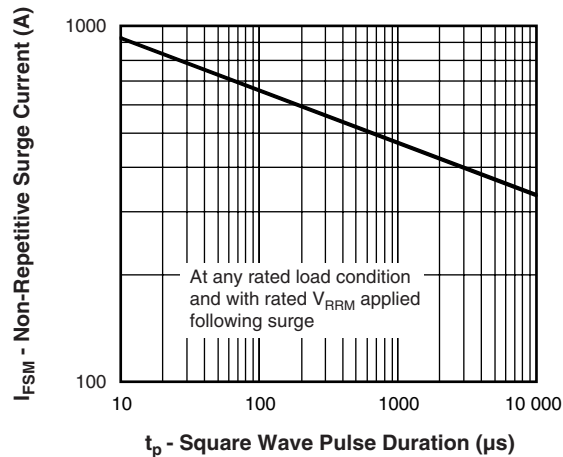


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

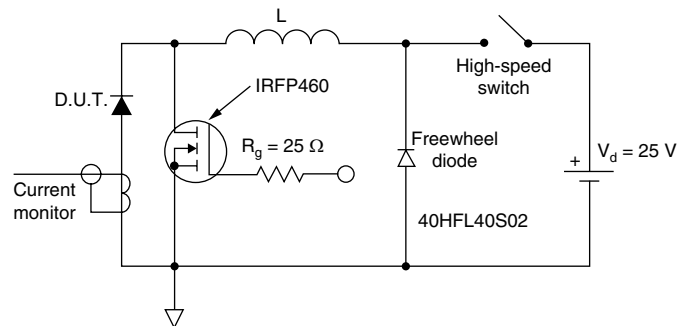


Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 10$ V

**ORDERING INFORMATION TABLE**

Device code	VS-	MBR	B	30	30	CT	L	TRL	PbF
	1	2	3	4	5	6	7	8	9

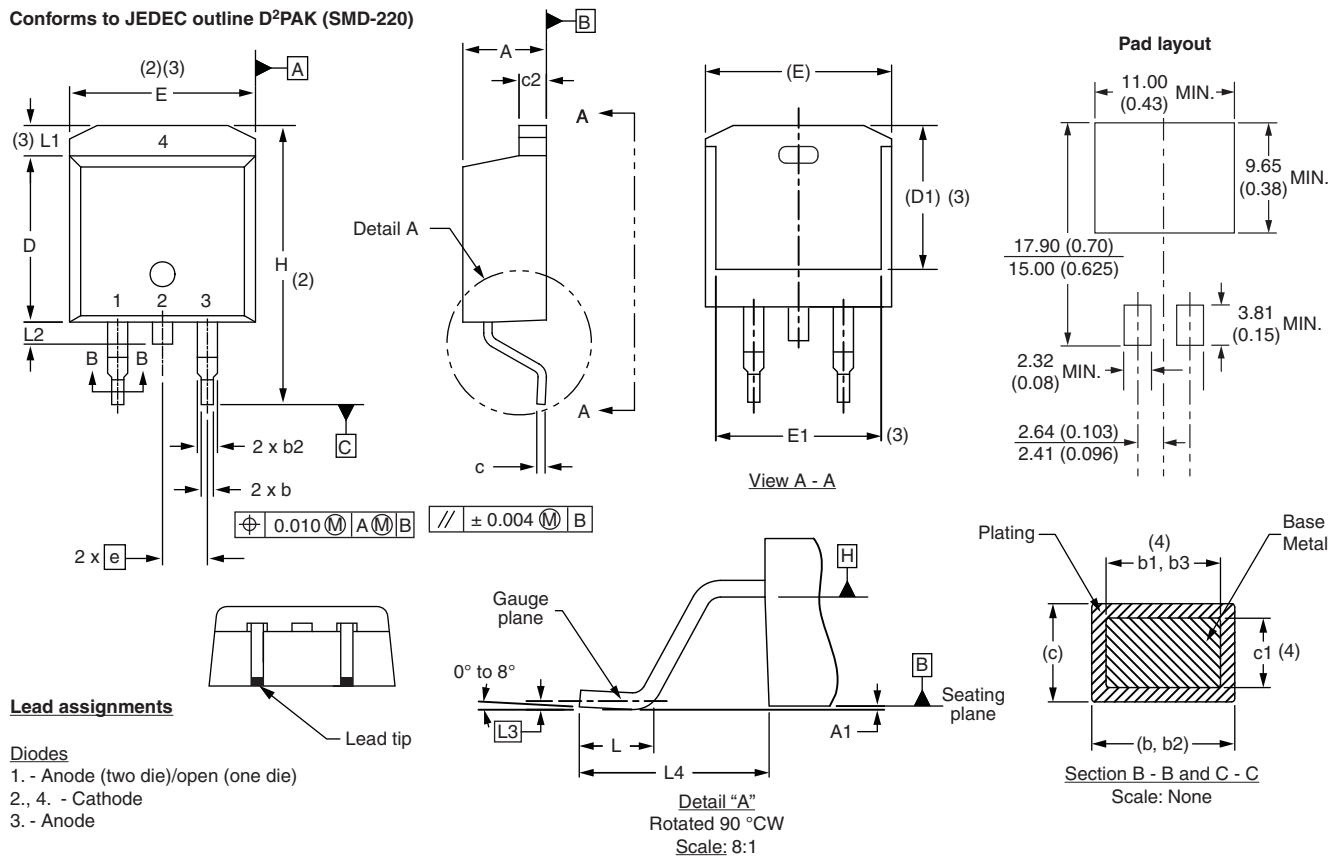
- | | | |
|---|---|--|
| 1 | - | HPP product suffix |
| 2 | - | Schottky MBR series |
| 3 | - | B = D ² PAK |
| 4 | - | Current rating (30 = 30 A) |
| 5 | - | Voltage rating (30 = 30 V) |
| 6 | - | CT = Center tap (dual) |
| 7 | - | L = Low V _F |
| 8 | - | <ul style="list-style-type: none">• None = Tube (50 pieces)• TRL = Tape and reel (left oriented - for D²PAK only)• TRR = Tape and reel (right oriented - for D²PAK only) |
| 9 | - | <ul style="list-style-type: none">• PbF = Lead (Pb)-free (for D²PAK tube)• P = Lead (Pb)-free (for D²PAK TRR and TRL) |

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC outline TO-263AB



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